**Code of A Share: 601166 Abbreviation of A Share: Industrial Bank Code: TEMP 2021-018**

**Code of Preferred Stock: 360005, 360012, 360032 Abbreviation of Preferred Stock: Industrial Preferred 1, Industrial Preferred 2, Industrial Preferred 3**

Industrial Bank Co., Ltd.

Announcement on Issuance and Listing of Relevant Bonds by the Hong Kong Branch under the USD 5 Billion Medium-term Notes Plan

The Board of Directors of the Company and all directors guarantee there’s no false account, misleading statement or material omissions of the announcement, and will be jointly and severally responsible for the truthfulness, accuracy and integrity of the announcement.

According to the resolution of Industrial Bank Co., Ltd. (hereinafter referred to as the "Company") on the issuance of financial bonds in 2018 Annual General Meeting of Shareholders, the Hong Kong branch of the Company recently completed the overseas issuance of USD 922 million equivalent USD and HKD bonds under the USD 5 billion medium-term notes plan, the raised funds are mainly used to provide financing and refinancing of qualified green assets for renewable energy, low-carbon and low-emission transportation, and to contribute to the realization of China's carbon neutral goals. The issuance is as follows: 1. USD-denominated senior unsecured bonds: USD 600 million with an annual interest rate of 0.875%, and the term until 2024; 2. HKD-denominated senior unsecured bonds: HKD 2.5 billion with an annual interest rate of 0.750%, and the term until 2024.

The above bonds will be listed on the Stock Exchange of Hong Kong Limited from June 11, 2021.

Hereby Announced.

Board of Directors of Industrial Bank Co., Ltd.

June 11, 2021